

REMARKS

Claims 1-8 are all the claims pending in the application.

Claims 3, 5, 7 and 8 have been rejected because of certain informalities.

Claims 1-8 are rejected under 35 U.S.C. § 102(b) as being anticipated by Kondo (5,283,468).

The Applicants traverse the rejections and request reconsideration.

Formal Matters

The Examiner is requested to consider the references filed as part of an IDS filed on March 19, 2003, and return a signed and initialed copy of the corresponding PTO Form 1449.

Claim Objections

The Applicants respectfully amend claims 3, 5, 7, and 8 to overcome the noted objections.

Rejection of claims 1-8 based on Kondo

Claim 1 requires a plurality of electronic devices to be connected to each other by conductive portions implemented by metal. Further, the devices that are connected by metal are insulated **from each other** by a resin layer.

The Examiner is believed to be mischaracterizing the teachings of Kondo. In Kondo, the resin layer does not insulate the devices that are connected by the metals from each other. For example, in Fig. 13(c) of Kondo, the circuits that are connected to each other by metal 107 are 101 and 104. However, the resin 207 insulates various circuits 101 from each other. The resin layer 207 does not insulate 101 from 104. In fact the gap between 101 and 104 is filled in by the

holding body 111. There is no teaching that 111 is a resin. While 207 is specifically disclosed to be a resin, 111 is simply disclosed to be an organic material (Kondo 16:45). Therefore, Kondo does not disclose that the electronic devices (that are connected to each other by metal) are insulated from each other by an adhesive, sealable patterned resin layer.

Further, the resin used in Kondo is thicker than the interval between the electric circuit component holding member and the other electric circuit component when connected to each other. Thus, since the resin is applied after the electric circuit component holding member and the other electric circuit component have been positioned, the resin never reaches the interior portion underneath the electric circuit component. Therefore, such a resin layer cannot be insulating the electrical devices from each other.

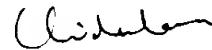
Claims 2-8 are dependant on claim 1 and are patentable at least for analogous reasons.

CONCLUSION

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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PATENT TRADEMARK OFFICE

Date: June 16, 2003

APPENDIX
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The claims are amended as follows:

3. (ONCE AMENDED) An assembly as claimed in claim 2, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer [would effect] effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

5. (ONCE AMENDED) An assembly as claimed in claim 4, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer [would effect] effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

7. (ONCE AMENDED) An assembly as claimed in claim 6, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer [would effect]

effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

8. (ONCE AMENDED) An assembly as claimed in claim 1, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer [would effect] effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.